ON Semiconductor

Is Now

Onsemi

To learn more about onsemi[™], please visit our website at <u>www.onsemi.com</u>

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product factures, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and asfety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or by customer's technical experts. onsemi products and actal performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application, Buyer shall indemnify and hold onsemi and its officers, employees, subsidiari



ON Semiconductor®

FDP6030BL/FDB6030BL N-Channel Logic Level PowerTrench[®] MOSFET

Features

General Description

G

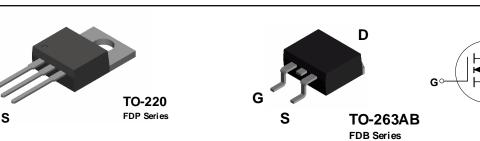
D

s been designed • Critical DC electrical paramet

This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\rm DS(on)}$ specifications resulting in DC/DC power supply designs with higher overall efficiency.

- 40 A, 30 V. $R_{DS(ON)} = 0.018 \Omega @ V_{GS} = 10 V$ $R_{DS(ON)} = 0.024 \Omega @ V_{GS} = 4.5 V.$
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- High performance trench technology for extremely low R_{DS(ON)}.
- 175°C maximum junction temperature rating.



Absolute Maximum Ratings T_c = 25°C unless otherwise noted

Symbol	Parameter	FDP6030BL	FDB6030BL	Units
V _{DSS}	Drain-Source Voltage	30		V
V _{GSS}	Gate-Source Voltage	±20		V
ID	Maximum Drain Current - Continuous (Note 1)	40		Α
	- Pulsed	1	20	
PD	Total Power Dissipation @ $T_c = 25^{\circ}C$	60		W
	Derate above 25°C	0.	36	W/°C
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-65 to +175		°C
Therma	I Characteristics			
$R_{\theta_{JC}}$	Thermal Resistance, Junction-to-Case	2	.5	°C/W
RθJA	Thermal Resistance, Junction-to-Ambient	62	2.5	°C/W

Package Marking and Ordering Information

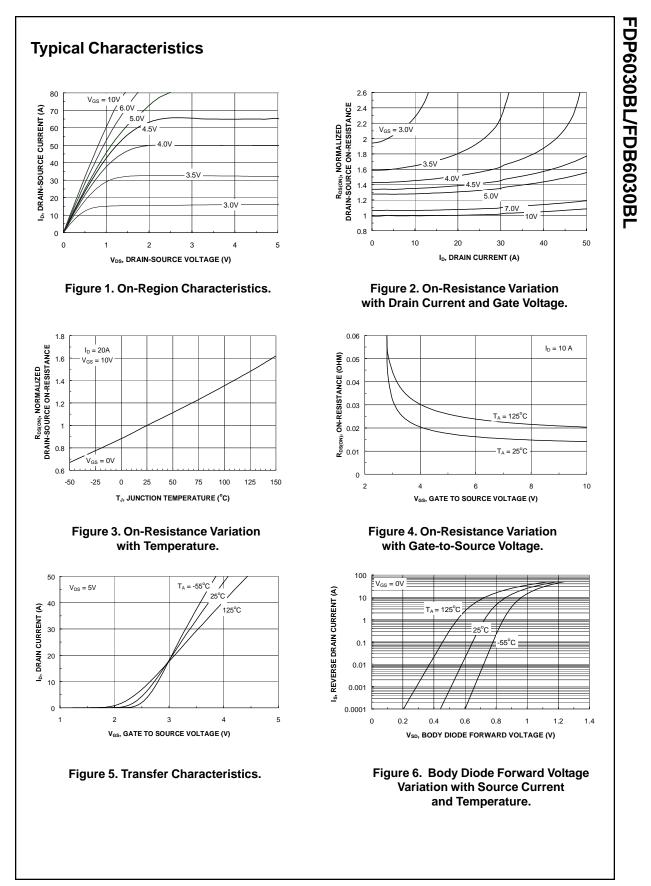
Device Marking	Device	Reel Size	Tape Width	Quantity
FDB6030BL	FDB6030BL	13"	24mm	800
FDP6030BL	FDP6030BL	Tube	N/A	45

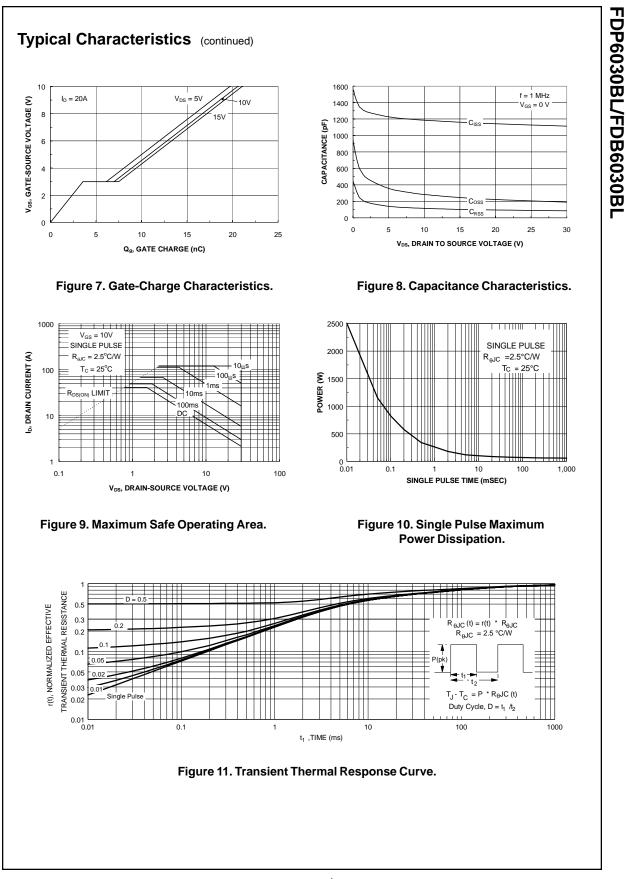
©2000 Semiconductor Components Industries, LLC. November-2017, Rev. 3

D

Parameter	Test Conditions	Min	Тур	Max	Units
OURCE AVALANCHE RATI	NGS (Note 1)				
Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 15 \text{ V}, \text{ I}_{D} = 40 \text{ A}$			150	mJ
Maximum Drain-Source Avalnche	e Current			40	А
octeristics					
Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V
Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, Referenced to 25° C		23		mV/°C
Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
Gate-Body Leakage Current, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
cteristics (Note 1)					
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1	1.6	3	V
Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu\text{A}$, Referenced to 25°C		-4.5		mV/°C
Static Drain-Source On-Resistance	$V_{GS} = 10 V, I_D = 20 A,$ $V_{GS} = 10 V, I_D = 20 A, T_J = 125^{\circ}C$ $V_{GS} = 4.5 V, I_D = 17 A$		0.015 0.021 0.019	0.018 0.030 0.024	Ω
On-State Drain Current	$V_{GS} = 10 \text{ V}, \text{ V}_{DS} = 10 \text{ V}$	40			А
Forward Transconductance	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		30		S
Characteristics					
	$V_{PC} = 15 V$, $V_{CC} = 0 V$		1160		pF
	f = 1.0 MHz				pF
					pF
		1			
	$V_{22} = 15 V I_2 = 1 A$		q	17	ns
	$V_{GS} = 10$ V, $R_{GEN} = 6 \Omega$				ns
Turn-Off Delay Time			23	37	ns
· • • · · · · · · · · · · · · · · · · ·			8	16	ns
Turn-Off Fall Time				47	nC
Turn-Off Fall Time Total Gate Charge	$V_{DS} = 15 V.$		12		
Total Gate Charge	V_{DS} = 15 V, I _D = 20 A, V _{GS} = 5 V		12 3.2	17	-
			12 3.2 3.7	17	nC nC
Total Gate Charge Gate-Source Charge Gate-Drain Charge	$I_{D} = 20 \text{ A}, \text{ V}_{GS} = 5 \text{ V}$		3.2	17	nC
Total Gate Charge Gate-Source Charge Gate-Drain Charge urce Diode Characteristics	$I_D = 20 \text{ A}, V_{GS} = 5 \text{ V}$ and Maximum Ratings		3.2		nC nC
Total Gate Charge Gate-Source Charge Gate-Drain Charge	$I_D = 20 \text{ A}, V_{GS} = 5 \text{ V}$ and Maximum Ratings		3.2	40	nC
	Maximum Drain-Source AvaInche cteristics Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse cteristics (Note 1) Gate Threshold Voltage Gate Threshold Voltage Temperature Coefficient Static Drain-Source On-Resistance On-State Drain Current	Maximum Drain-Source Avalnche CurrentcteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 250 \text{ µA}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ µA}, \text{ Referenced to } 25^{\circ}\text{C}$ Zero Gate Voltage Drain Current $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ Gate-Body Leakage Current, Forward $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \text{ µA}$ Gate Threshold Voltage $I_D = 250 \text{ µA}, \text{ Referenced to } 25^{\circ}\text{C}$ Temperature Coefficient $I_D = 250 \text{ µA}, \text{ Referenced to } 25^{\circ}\text{C}$ Static Drain-Source $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A},$ On-Resistance $V_{GS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$ Forward Transconductance $V_{DS} = 5 \text{ V}, I_D = 20 \text{ A}$ CharacteristicsInput CapacitanceInput Capacitance $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHzf = 1.0 MHzReverse Transfer Capacitance $V_{DD} = 15 \text{ V}, I_D = 1 \text{ A},$ Turn-On Delay Time $V_{DD} = 15 \text{ V}, I_D = 1 \text{ A},$	Maximum Drain-Source AvaInche Current cteristics Drain-Source Breakdown Voltage $V_{GS} = 0 V, I_D = 250 \mu A$ 30 Breakdown Voltage Temperature Coefficient $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ 30 Zero Gate Voltage Drain Current $V_{DS} = 24 V, V_{GS} = 0 V$ 30 Gate-Body Leakage Current, Forward $V_{GS} = 20 V, V_{DS} = 0 V$ 30 Gate-Body Leakage Current, Forward $V_{GS} = -20 V, V_{DS} = 0 V$ 30 Gate-Body Leakage Current, Reverse $V_{GS} = -20 V, V_{DS} = 0 V$ 30 Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \mu A$ 1 Gate Threshold Voltage $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ 1 Gate Threshold Voltage $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ 1 Gate Threshold Voltage $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ 1 Static Drain-Source $V_{GS} = 10 V, I_D = 20 A$, $V_{GS} = 10 V, I_D = 20 A$, $T_J = 125^{\circ}C$ 1 On-State Drain Current $V_{GS} = 5 V, I_D = 10 V$ 40 Forward Transconductance $V_{DS} = 15 V, V_{GS} = 0 V,$ 1 Input Capacitance $V_{DS} = 15 V, V_{GS} = 0 V,$ 1 Input Capacitance $V_{DD} $	Maximum Drain-Source Avalnche CurrentcteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 V, I_D = 250 \mu A$ 30Breakdown Voltage Temperature Coefficient $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ 23Zero Gate Voltage Drain Current $V_{DS} = 24 V, V_{GS} = 0 V$ 30Gate-Body Leakage Current, Forward $V_{GS} = 20 V, V_{DS} = 0 V$ 30Gate-Body Leakage Current, Reverse $V_{GS} = -20 V, V_{DS} = 0 V$ 30Cteristics (Note 1) $V_{DS} = V_{GS}, I_D = 250 \mu A$ 11.6Gate Threshold Voltage Cate Threshold Voltage $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ -4.5Cteristics (Note 1) $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ -4.5Gate Threshold Voltage Temperature Coefficient $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ -4.5Static Drain-Source On-Resistance $V_{GS} = 10 V, I_D = 20 A, V_{JS} = 125^{\circ}C$ 0.015On-State Drain Current $V_{GS} = 10 V, I_D = 20 A, V_{JS} = 10 V, I_D = 20 A$ 30Characteristics $V_{DS} = 5 V, I_D = 10 V$ 40Forward Transconductance $V_{DS} = 5 V, I_D = 20 A$ 30Characteristics $I_{D} = 15 V, V_{GS} = 0 V, I_{D} = 250$ 1160Output Capacitance $V_{DS} = 15 V, I_D = 1 A, V_{DS} = 10 V, I_D = 20 Q$ 100Characteristics $(Note 1)$ 100Turn-On Delay Time $V_{DD} = 15 V, I_D = 1 A, V_{DS} = 10 V, I_D = 10 P, I_D V$ 9	Maximum Drain-Source Avalnche Current40CteristicsVGS = 0 V, ID = 250 μ A30Drain-Source Breakdown VoltageVGS = 0 V, ID = 250 μ A, Referenced to 25°C23Breakdown Voltage Temperature CoefficientID = 250 μ A, Referenced to 25°C23Zero Gate Voltage Drain CurrentVDS = 24 V, VGS = 0 V1Gate-Body Leakage Current, ReverseVGS = 20 V, VDS = 0 V100Forward Gate-Body Leakage Current, ReverseVGS = -20 V, VDS = 0 V-100Cteristics (Note 1)ID = 250 μ A, Referenced to 25°C-4.5Gate Threshold Voltage On-ResistanceVDS = VGS, ID = 250 μ A11.6On-ResistanceVDS = 10 V, ID = 20 A, VGS = 10 V, ID = 20 A, On-Resistance0.0150.018 0.019On-State Drain CurrentVGS = 10 V, VDS = 10 V404040Forward TransconductanceVDS = 5 V, ID = 20 A3030Characteristics Reverse Transfer CapacitanceVDS = 15 V, VGS = 0 V, 100 Hz1160Output Capacitance Reverse Transfer CapacitanceVDS = 15 V, ID = 1 A, VDD = 15 V, ID = 1 A, VDD = 15 V, ID = 1 A,9Turn-On Delay TimeVDD = 15 V, ID = 1 A, VDD = 15 V, ID = 1 A, VDD = 15 V, ID = 1 A, VDD = 15 V, ID = 1 A,9

FDP6030BL/FDB6030BL





www.onsemi.com 4

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor haves, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such uninten

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative